PCN Number:	20190924000 PCN Date: Sept. 27, 2019						019	
Title: Datasheet for								
Customer Contact:	·			ep	t:	Quality Services		
Change Type:								
Assembly Site		Design				Wafer	Bump Site	
Assembly Process		Data Sheet				Wafer	Bump Material	
Assembly Materials		Part number change					Bump Process	
Mechanical Specification		Test Site		Щ	_		Fab Site	
Packing/Shipping/Labeling		est Process		\sqcup	Ц		Fab Materials	
						Wafer	Fab Process	
Notification Details								
Description of Change: Texas Instruments Incorporated is announcing an information only notification.								
The product datasheet(s) is being updated as summarized below. The following change history provides further details.								
INSTRUMENTS OPA990, OPA2990, OPA6 SBOS933D - FEBRUARY 2019 - REVISED JULY								
Changes from Revision C (May 2019) to Revision D								
Removed preview notation	from OPA2990 DSG	nackage (\M	SON) in the Pin Cont	iaura	tio	n and Fu	nctions section 4	
•			•	_				
Added SHUTDOWN to Electrical Characteristics table								
Added Shutdown section to the Detailed Description section								
The datasheet number will be changing.								
Device Family		Change From:		Change To:				
					January 2 1 5 1			
OPA990, OPA2990, OPA	SBOS93	SBOS933C			SBOS933D			
These changes may be reviewed at the datasheet links provided.								
http://www.ti.com/prod	uct/OPA990							
Reason for Change:								
To accurately reflect device characteristics.								
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):								
No anticipated impact. This is a specification change announcement only. There are no changes								
to the actual device.								
Changes to product identification resulting from this PCN:								
None.								
Product Affected:								
OPA2990IDR	OPA2990IDSGR		ODV3000ID/V	OPA2990IPWR			DPA2990SIDGSR	
							OPA990IDCKR	
OPA4990IDR	OPA4990IPWR			PA990IDBVR				
OPA990SIDBVR	POPA2990SIDGSR			POPA4990IDR			POPA4990IPWR	
POPA990IDBVR	POPA990IDCKR		POPA990SIDB\					

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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